

WHAT IS CLAIMED IS:

1. A method of fastening a 12-inch silicon electrode used in semiconductor etching process equipment, the method
5 comprising:

(1) forming a plurality of bushing tabs on a silicon electrode (100) to fasten the silicon electrode (100) used in the semiconductor etching process equipment and fastening a plurality of bushings (110) to the plurality of bushing tabs,
10 respectively;

(2) positioning and placing the silicon electrode (100) on a back plate (200) of the semiconductor etching process equipment to fasten the silicon electrode (100) to which the plurality of bushings (110) are fastened and fixed in step (1);
15 and

(3) fastening and fixing the back plate (200) and the silicon electrode (100) through a plurality of bushing fastening screws (300) in a state in which the silicon electrode (100) is positioned and placed on the back plate
20 (200) in step (2),

wherein in step (1), the plurality of bushings (110) are fastened and fixed to the plurality of bushing tabs formed on the silicon electrode (100) to fasten the silicon electrode (100) used in the semiconductor etching process equipment, the
25 plurality of bushings (110) are made of engineering plastic,

each of the plurality of bushings (110) is fastened to each of the plurality of bushing tabs of the silicon electrode (100) used in the semiconductor etching process equipment and is fastened to the silicon electrode (100) by applying a bonding agent free of contamination and having adhesive force on an outer diameter surface thereof on which a first screw thread is formed, and

in step (3), the plurality of bushing fastening screws (300) are fastened to the silicon electrode (100) by passing through a plurality of screw holes at the bottom of the back plate (200).

2. The method of claim 1, wherein the silicon electrode (100) is a 12-inch silicon electrode used in the semiconductor etching process equipment, and is composed of one set of an inner silicon electrode (120) to which the plurality of bushings (110) for fastening to the back plate (200) are fastened and fixed and an outer silicon electrode (130).

3. The method of claim 1 or 2, wherein each of the plurality of bushing tabs comprises a second screw thread formed by machining an inner diameter of each of the plurality of bushing tabs for fastening and fixing to a bushing of the plurality of bushings (110).

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4. The method of claim 3, wherein the first screw thread is configured to insert and fasten to the second screw thread so that each of the plurality of bushings (110) is fastened to each of the plurality of bushing tabs of the silicon electrode
5 (100).